

# Lead-free Green 74AUP1G09 SINGLE 2 INPUT POSITIVE AND GATE WITH OPEN DRAIN OUTPUT

#### Description

The Advanced, Ultra Low Power (AUP) CMOS logic family is designed for low power and extended battery life in portable applications.

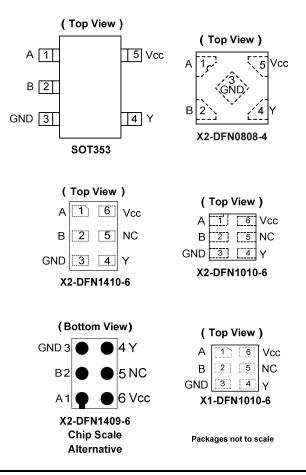
The AUP1G09 is a single AND gate with an open drain output designed for operation over a power supply range of 0.8V to 3.6V. The device is fully specified for partial power down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output preventing damaging current backflow when the device is powered down. The gate performs the positive Boolean function:

$$Y = A \bullet B$$
 or  $Y = \overline{\overline{A} + \overline{B}}$ 

#### **Features**

- Advanced Ultra Low Power (AUP) CMOS
- Supply Voltage Range from 0.8V to 3.6V
- 4mA Output Drive at 3.0V
- Low Static Power Consumption  $I_{CC} < 0.9 \mu A$
- Low Dynamic Power Consumption C<sub>PD</sub> = 6 pF (Typical at 3.6V)
- Schmitt Trigger Action at all inputs makes the circuit tolerant for slower input rise and fall time. The hysteresis is typically 250 mV at V<sub>CC</sub> = 3.0V.
- IOFF Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
   2000-V Human Body Model (A114)
   Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Leadless Packages Named per JESD30E
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### Pin Assignments



#### Applications

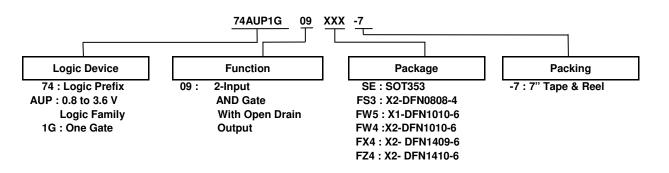
- Suited for Battery and Low Power Needs
- Wide array of products such as:
  - Tablets, E-readers
  - Cell Phones, Personal Navigation / GPS
  - MP3 Players ,Cameras, Video Recorders
  - PCs, Ultrabooks, Notebooks, Netbooks
  - Computer Peripherals, Hard Drives, SSDs, CD/DVD ROMs
  - TVs, DVDs, DVRs, Set-Top Boxes

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



## **Ordering Information**



Device	Package	Package	Package	7" Tape	and Reel
Device	Code	(Notes 4 & 5)	es 4 & 5) Size		Part Number Suffix
74AUP1G09SE-7	SE	SOT353	2.0mm x 2.0mm x 1.1mm 0.65 mm lead pitch	3,000/Tape & Reel	-7
74AUP1G09FS3-7	FS3	X2-DFN0808-4	0.8mm x 0.8mm x 0.35mm 0.5 mm pad pitch (diamond)	5,000/Tape & Reel	-7
74AUP1G09FW5-7	FW5	X1-DFN1010-6	1.0mm x 1.0mm x 0.5mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74AUP1G09FW4-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74AUP1G09FX4-7	FX4	X2-DFN1409-6 Chip Scale Alternative	1.4mm x 0.9mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7
74AUP1G09FZ4-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7

Notes: 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at

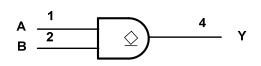
http://www.diodes.com/datasheets/ap02001.pdf.

5. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Pin Descriptions**

Pin Name	Function
А	Data Input
В	Data Input
GND	Ground
Y	Data Output
Vcc	Supply Voltage

## Logic Diagram



## **Function Table**

Inpu	Output	
Α	В	Y
L	L	L
L	Н	L
Н	L	L
Н	Н	Z



Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
V <sub>CC</sub>	Supply Voltage Range	-0.5 to +4.6	V
VI	Input Voltage Range	-0.5 to +4.6	V
Vo	Voltage applied to output in High or Low State	-0.5 to +4.6	V
I <sub>IK</sub>	Input Clamp Current VI < 0	50	mA
I <sub>ОК</sub>	Output Clamp Current (V <sub>O</sub> < 0)	50	mA
lo	Continuous Output Current (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±20	mA
Icc	Continuous Current Through V <sub>CC</sub>	50	mA
I <sub>GND</sub>	Continuous Current Through GND	-50	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C

## **Absolute Maximum Ratings** (Notes 6 & 7) ( $@T_A = +25 \degree$ C, unless otherwise specified.)

Notes:

6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

## Recommended Operating Conditions (Note 8) (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

Symbol	Pa	rameter	Min	Max	Unit
Vcc	Operating Voltage		0.8	3.6	V
VI	Input Voltage		0	3.6	V
Vo	Output Voltage		0	3.6	V
		$V_{CC} = 0.8V$	—	20	μA
		V <sub>CC</sub> = 1.1V	—	1.1	
		$V_{CC} = 1.4V$	—	1.7	
I <sub>OL</sub>	Low-Level Output Current	V <sub>CC</sub> = 1.65V	—	1.9	mA
		V <sub>CC</sub> = 2.3V	—	3.1	
		V <sub>CC</sub> = 3.0V	—	4	
Δt/ΔV	Input Transition Rise or Fall Rate	V <sub>CC</sub> = 0.8V to 3.6V	—	200	ns/V
T <sub>A</sub>	Operating Free-Air Temperature		-40	125	°C

Note: 8. Unused inputs should be held at  $V_{\mbox{\tiny CC}}$  or Ground.



## Electrical Characteristics (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

Cumula al	Deverseder	Test Canditions	N/	T <sub>A</sub> =	+25 <i>°</i> C	T <sub>A</sub> = -40 °	C to +85 <i>°</i> C	11	
Symbol	Parameter	Test Conditions	Vcc	Min	Max	Min	Max	Unit	
		—	0.8V to 1.65V	0.80 x V <sub>CC</sub>	—	0.80 x V <sub>CC</sub>	—		
VIH	High-Level	_	1.65V to 1.95V	0.65 x V <sub>CC</sub>	—	0.65 x V <sub>CC</sub>	—	v	
VIH	Input Voltage	_	2.3V to 2.7V	1.6	_	1.6	—	v	
		—	3.0V to 3.6V	2.0	_	2.0	_		
		—	0.8V to 1.65V		$0.30 \times V_{CC}$		$0.30 \times V_{CC}$		
VIL	Low-Level	—	1.65V to 1.95V	—	0.35 x V <sub>CC</sub>	_	$0.35 \times V_{CC}$	v	
۷IL	Input voltage	_	2.3V to 2.7V	—	0.7	_	0.7	v	
		_	3.0V to 3.6V		0.9	_	0.9		
		$I_{OL} = 20 \mu A$	0.8V to 3.6V	—	0.1	_	0.1		
		I <sub>OL</sub> = 1.1mA	1.1V	—	0.3 x V <sub>CC</sub>	_	0.3 x V <sub>CC</sub>		
		I <sub>OL</sub> = 1.7mA	1.4V	—	0.31	_	0.37		
.,	Low-Level	I <sub>OL</sub> = 1.9mA	1.65V	—	0.31	-	0.35		
V <sub>OL</sub>	L Output Voltage	I <sub>OL</sub> = 2.3mA	0.01/	—	0.31	_	0.33	V	
	. enage	I <sub>OL</sub> = 3.1mA	2.3V		0.44	_	0.45		
		I <sub>OL</sub> = 2.7mA	01/	_	0.31	_	0.33		
		I <sub>OL</sub> = 4mA	3V		0.44	_	0.45		
I <sub>I</sub>	Input Current	A or B Input $V_1 = GND$ to 3.6V	0V to 3.6V	_	± 0.1	_	± 0.5	μA	
IOFF	Power Down Leakage Current	$V_1$ or $V_0 = 0V$ to 3.6V	0	_	± 0.2	_	± 0.5	μA	
I <sub>OZ</sub>	Z State Leakage Current	$V_O = 3.6V$ $V_i = 3.6V$	3.6V	_	± 0.2	_	± 0.5	μA	
ΔI <sub>OFF</sub>	Delta Power Down Leakage Current	$V_1$ or $V_0 = 0V$ to 3.6V	0V to 0.2V	_	0.2		0.6	μA	
Icc	Supply Current	$V_I = GND \text{ or } V_{CC}$ $I_O = 0$	0.8V to 3.6V		0.5		0.9	μA	
$\Delta I_{CC}$	Additional Supply Current	Input at V <sub>CC</sub> -0.6V	3.3V	_	40	_	50	μA	



## **Electrical Characteristics** (continued) (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

Cumhal	Parameter	Test Conditions	V	T <sub>A</sub> = -40 °C	C to +125℃	Unit
Symbol	Parameter	Test Conditions	Vcc	Min	Max	Unit
		-	0.8V to 1.65V	0.80 x V <sub>CC</sub>	—	
VIH	High-Level Input	_	1.65V to 1.95V	0.70 x V <sub>CC</sub>	—	V
VIH	Voltage	_	2.3V to 2.7V	1.6	—	Ì
		—	3.0V to 3.6V	2.0	—	
		—	0.8V to 1.65V	_	$0.25 \times V_{CC}$	
<b>M</b>	V <sub>IL</sub> Low-Level Input Voltage	—	1.65V to 1.95V	—	0.35 x V <sub>CC</sub>	V
VIL		_	2.3V to 2.7V	—	0.7	v
		_	3.0V to 3.6V	_	0.9	
		$I_{OL} = 20 \ \mu A$	0.8V to 3.6V	—	0.11	
		I <sub>OL</sub> = 1.1 mA	1.1V	—	0.3 x V <sub>CC</sub>	
	I <sub>OL</sub> = 1.7 mA	1.4V	—	0.41		
	Low-Level Output	I <sub>OL</sub> = 1.9 mA	1.65V	_	0.39	V
V <sub>OL</sub>	Voltage	I <sub>OL</sub> = 2.3 mA	0.01/	_	0.36	V
		I <sub>OL</sub> = 3.1 mA	- 2.3V	—	0.50	
		I <sub>OL</sub> = 2.7 mA		_	0.36	
		$I_{OL} = 4 \text{ mA}$	- 3V	_	0.50	
I,	Input Current	A or B Input VI = GND to 3.6V	0V to 3.6V	_	± 0.75	μA
IOFF	Power Down Leakage Current	$V_{I}$ or $V_{O} = 0V$ to 3.6V	0	_	± 3.5	μA
loz	Z State Leakage Current	$V_{O} = 3.6V$ $V_{i} = 3.6V$	3.6V		± 1.5	μA
$\Delta I_{OFF}$	Delta Power Down Leakage Current	$V_{I}$ or $V_{O} = 0V$ to 3.6V	0V to 0.2V	_	± 2.5	μA
Icc	Supply Current	$V_I = GND \text{ or } V_{CC}, I_O = 0$	0.8V to 3.6V	_	3.0	μA
ΔI <sub>CC</sub>	Additional Supply Current	Input at V <sub>CC</sub> -0.6V	3.3V	_	75	μA



## **Switching Characteristics**

C <sub>L</sub> =5pF, See	Figure 1										
Parameter	From	то	V <sub>cc</sub>	T <sub>A</sub> = +25 ℃			T <sub>A</sub> = -40 ℃ to +85 ℃		T <sub>A</sub> = -40 ℃ to +125 ℃		Unit
Falameter	Input	OUTPUT		Min	Тур	Max	Min	Max	Min	Max	Unit
			0.8V		13.5	—	—	—	_	I	
		Y	1.2V ± 0.1V	1.9	4.6	10.4	1.8	11.4	1.8	12.6	- ns -
+	۸		1.5V ± 0.1V	1.5	3.3	6.5	1.4	7.4	1.4	8.2	
t <sub>pd</sub>	A		1.8V ± 0.15V	1.2	2.9	5.1	1.1	5.9	1.1	6.5	
			2.5V ± 0.2V	1.0	2.4	4.4	0.9	4.6	0.9	4.9	
			3.3V ± 0.3V	0.9	2.3	4.0	0.8	4.5	0.8	4.9	

#### CL=10pF, See Figure 1

Parameter	From	то	V <sub>cc</sub>	T <sub>A</sub> = +25 ℃			T <sub>A</sub> = -40 ℃ to +85 ℃		T <sub>A</sub> = -40 ℃ to +125 ℃		Unit
Faranielei	Input OUTPUT	OUTPUT		Min	Тур	Max	Min	Max	Min	Max	onne
			0.8V	_	16.3	_	_	—	_	_	
		Y	1.2V ± 0.1V	2.3	5.6	12.3	2.1	13.7	2.1	15.1	ns
	٨		1.5V ± 0.1V	1.8	4.1	7.6	1.7	8.8	1.7	9.7	
t <sub>pd</sub>	A Y		1.8V ± 0.15V	1.6	3.2	7.3	1.4	7.1	1.4	7.0	
			2.5V ± 0.2V	1.4	2.9	6.1	1.2	6.4	1.2	5.9	
		3.3V ± 0.3V	1.3	2.9	5.7	1.1	5.4	1.1	5.9		

#### C<sub>L</sub>=15pF, See Figure 1

Paramotor	Parameter From TO Input OUTPU	то	V <sub>cc</sub>	T <sub>A</sub> = +25 ℃			T <sub>A</sub> = -40 ℃ to +85 ℃		T <sub>A</sub> = -40 ℃ to +125 ℃		Unit
Falametei		OUTPUT		Min	Тур	Max	Min	Max	Min	Max	Onit
			0.8V	_	19.0	—	—	—	_	_	
		Y	1.2V ± 0.1V	2.6	7.6	14.2	2.4	15.8	2.4	17.4	ns
+	۸		1.5V ± 0.1V	2.1	6.5	12.1	1.9	12.7	1.9	12.9	
t <sub>pd</sub>	A		1.8V ± 0.15V	1.9	5.5	9.6	1.7	10.1	1.7	10.3	
			2.5V ± 0.2V	1.6	4.6	8.1	1.5	9.1	1.5	9.3	
			3.3V ± 0.3V	1.6	4.1	7.5	1.4	8.3	1.4	9.1	

#### CL=30pF, See Figure 1

Parameter	From	то	V <sub>cc</sub>	-	T <sub>A</sub> = +25 ℃			T <sub>A</sub> = -40 ℃ to +85 ℃		T <sub>A</sub> = -40 ℃ to +125 ℃	
Farameter	Input OUTPUT	OUTPUT		Min	Тур	Max	Min	Max	Min	Max	Unit
			0.8V	_	27	_	_	—	_	—	
		Y	1.2V ± 0.1V	3.6	9.5	19.5	3.2	21.8	3.2	24	ns
	٨		1.5V ± 0.1V	2.9	8.5	16.1	2.6	13.6	2.6	15	
t <sub>pd</sub>	A		1.8V ± 0.15V	2.6	7.7	15.2	2.3	13.3	2.3	14.6	
			2.5V ± 0.2V	2.4	7	13.1	2.1	13.3	2.1	13.5	
			3.3V ± 0.3V	2.3	6.5	12.7	2.1	12.9	2.1	12.9	



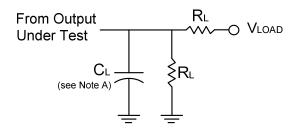
## **Operating and Package Characteristics** (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

	Parameter	Test Conditio		Vcc	Тур	Unit
				0.8V	6.5	
				1.2V ± 0.1V	6.3	
~	Power Dissipation	f = 1MH	lz	1.5V ± 0.1V	6.3	~_
C <sub>pd</sub>	Capacitance	No Loa	ld	1.8V ± 0.15V	6.2	pF
			2.5V ± 0.2V	6.2		
			3.3V ± 0.3V	6.1		
Ci	Input Capacitance	$V_i = V_{CC}$ or	GND	0V or 3.3V	1.5	pF
		SOT353			371	
		X2-DFN0808-4		—	430	
0	Thermal Resistance	X1-DFN1010-6			435	°C/M
$\theta_{JA}$	Junction-to-Ambient	X2-DFN1010-6	(Note 9)	—	445	-C/W
		X2-DFN1409-6		—	470	
		X2-DFN1410-6		—	460	
		SOT353		—	143	
		X2-DFN0808-4		—	240	
0	θ <sub>JC</sub> Thermal Resistance Junction-to-Case	X1-DFN1010-6	(Note 0)	_	250	°C/W
AlC		X2-DFN1010-6	(Note 9)	—	250	-C/W
		X2-DFN1409-6	] [	—	275	
		X2-DFN1410-6	1	_	265	

Note: 9. Test condition for each of the six package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

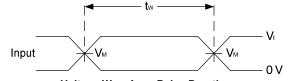


## **Parameter Measurement Information**

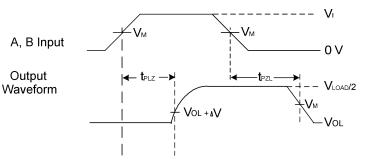


TEST	Condition
$t_{PLZ}$ (see Notes D and E) $t_{PZL}$ (see Notes D and F)	Vload Vload

Vcc	In	puts	VM	V <sub>M</sub> V <sub>LOAD</sub>	CL	RL	VA
	VI	t <sub>r</sub> /t <sub>f</sub>	• 101	LOAD	ΨL		
0.8 V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	2 X V <sub>CC</sub>	5, 10, 15, 30 pF	5ΚΩ	0.1V
1.2 V±0.1 V	V <sub>CC</sub>	≤3ns	V <sub>cc</sub> /2	2 X V <sub>CC</sub>	5, 10, 15, 30 pF	5ΚΩ	0.1V
1.5 V±0.1 V	V <sub>CC</sub>	≤3ns	V <sub>cc</sub> /2	2 X V <sub>CC</sub>	5, 10, 15, 30 pF	5ΚΩ	0.15V
1.8 V±0.15 V	V <sub>CC</sub>	≤3ns	V <sub>cc</sub> /2	2 X V <sub>CC</sub>	5, 10, 15, 30 pF	5ΚΩ	0.15V
2.5 V±0.2 V	V <sub>CC</sub>	≤3ns	V <sub>cc</sub> /2	2 X V <sub>CC</sub>	5, 10, 15, 30 pF	5ΚΩ	0.15V
3.3 V±0.3 V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	2 X V <sub>CC</sub>	5, 10, 15, 30 pF	5KΩ	0.3V



Voltage Waveform Pulse Duration



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

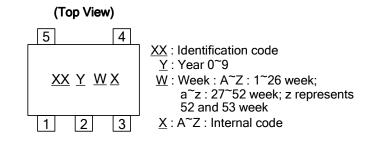
Figure 1 Load Circuit and Voltage Waveforms

- Notes: A. Includes test lead and test apparatus capacitance.
  - B. All pulses are supplied at pulse repetition rate  $\leq$  10MHz.
  - C. Inputs are measured separately one transition per measurement.
  - D.  $t_{\text{PLH}}$  and  $t_{\text{PHL}}$  are the same as  $t_{\text{PD.}}$



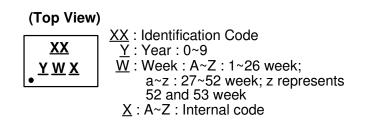
#### **Marking Information**

#### (1) SOT353



Part Number	Package	Identification Code
74AUP1G09SE	SOT353	XR

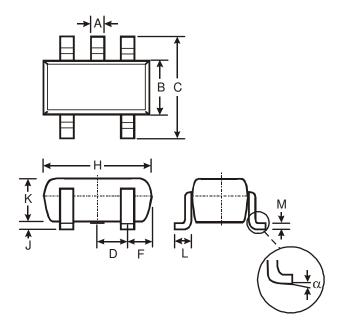
(2) X2-DFN0808-4, X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6 and X2-DFN1410-6



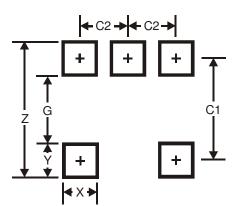
Part Number	Package	Identification Code
74AUP1G09FS3	X2-DFN0808-4	YU
74AUP1G09FW5	X1-DFN1010-6	Q8
74AUP1G09FW4	X2-DFN1010-6	XR
74AUP1G09FX4	X2-DFN1409-6	HG
74AUP1G09FZ4	X2-DFN1410-6	XR



## SOT353 Package Outline Dimensions and Suggested Pad Layout



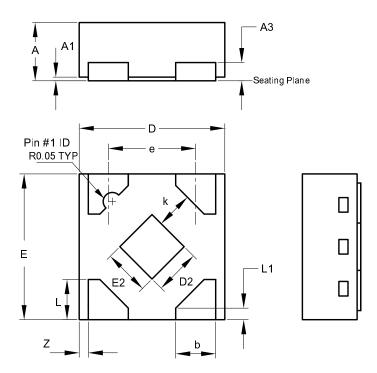
	SOT353					
Dim	Min	Max	Тур			
Α	0.10	0.30	0.25			
В	1.15	1.35	1.30			
С	2.00	2.20	2.10			
D	0.65 Typ					
F	0.40	0.45	0.425			
н	1.80	2.20	2.15			
J	0	0.10	0.05			
К	0.90	1.00	1.00			
L	0.25	0.40	0.30			
М	0.10	0.22	0.11			
α	0°	8°	-			
A	All Dimensions in mm					



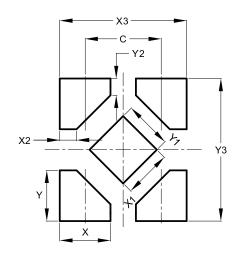
Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65



## X2-DFN0808-4 Package Outline Dimensions and Suggested Pad Layout



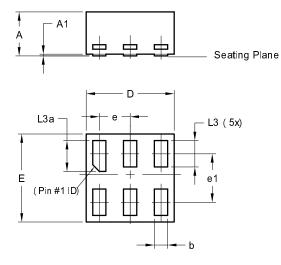
	X2-DFN0808-4					
Dim	Min	Max	Тур			
Α	0.25	0.35	0.30			
A1	0	0.04	0.02			
A3	-	-	0.13			
b	0.17	0.27	0.22			
D	0.75	0.85	0.80			
D2	0.15	0.35	0.25			
E	0.75	0.85	0.80			
E2	0.15	0.35	0.25			
е	-	-	0.48			
K	0.20	-	-			
L	0.17	0.27	0.22			
L1	0.02	0.12	0.07			
Z	-	-	0.05			
All	Dimens	sions in	mm			



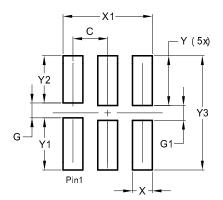
Dimensions	Value	
С	0.480	
Х	0.320	
X1	0.300	
X2	0.106	
X3	0.800	
Y	0.320	
Y1	0.300	
Y2	0.106	
Y3	0.900	



## X1-DFN1010-6 Package Outline Dimensions and Suggested Pad Layout



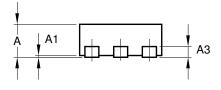
X1-DFN1010-6					
Dim	Min	Max	Тур		
Α	-	0.50	0.39		
A1	-	0.04	-		
b	0.12	0.20	0.15		
D	0.95	1.050	1.00		
Е	0.95	1.050	1.00		
е	0.35 BSC				
e1		0.55 B	SC		
L3	0.27	0.30	0.30		
L3a	0.32	0.40	0.35		
All	All Dimensions in mm				

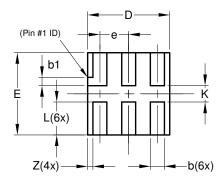


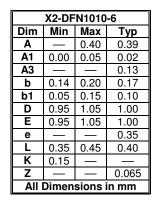
Dimensions	Value (in mm)	
С	0.350	
G	0.150	
G1	0.150	
Х	0.200	
X1	0.900	
Y	0.500	
Y1	0.525	
Y2	0.475	
Y3	1.150	

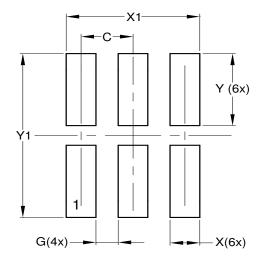


## X2-DFN1010-6 Package Outline Dimensions and Suggested Pad Layout





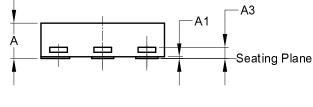


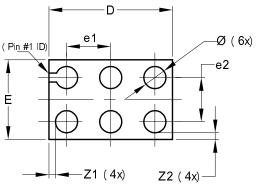


Dimensions	Value (in mm)	
С	0.350	
G	0.150	
X	0.200	
X1	0.900	
Y	0.550	
Y1	1.250	

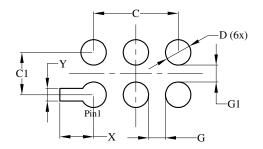


## X2-DFN1409-6 Package Outline Dimensions and Suggested Pad Layout





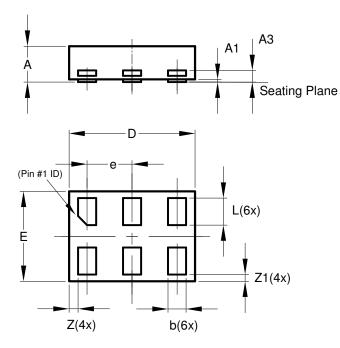
	X2-DFN1409-6					
Dim	Min	Max	Тур			
Α	-	0.40	0.39			
A1	0	0.05	0.02			
A3	-	-	0.13			
Ø	0.20	0.30	0.25			
D	1.35	1.45	1.40			
Е	0.85	0.95	0.90			
e1	-	-	0.50			
e2	-	-	0.50			
Z1	-	-	0.075			
Z2	-	-	0.075			
All Dimensions in mm						



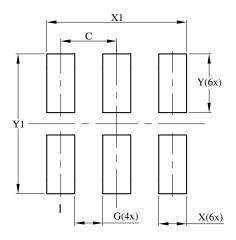
Dimensions	Value (in mm)
С	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
Х	0.400
Ŷ	0.150



## X2-DFN1410-6 Package Outline Dimensions and Suggested Pad Layout



X2-DFN1410-6				
Dim	Min	Max	Тур	
Α		0.40	0.39	
A1	0.00	0.05	0.02	
A3		_	0.13	
b	0.15	0.25	0.20	
D	1.35	1.45	1.40	
Е	0.95	1.05	1.00	
e			0.50	
L	0.25	0.35	0.30	
Z	_	_	0.10	
Z1	0.045	0.105	0.075	
All Dimensions in mm				



Dimensions	Value (in mm)
С	0.500
G	0.250
Х	0.250
X1	1.250
Y	0.525
Y1	1.250



#### **IMPORTANT NOTICE**

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

#### LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2015, Diodes Incorporated

www.diodes.com

## **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Logic Gates category:

Click to view products by Diodes Incorporated manufacturer:

Other Similar products are found below :

5962-8769901BCA 74HC85N NL17SG08P5T5G NL17SG32DFT2G NLU1G32AMUTCG NLV7SZ58DFT2G NLVHC1G08DFT1G NLVVHC1G14DTT1G NLX2G08DMUTCG NLX2G08MUTCG MC74HCT20ADR2G 091992B 091993X 093560G 634701C 634921A NL17SG32P5T5G NL17SG86DFT2G NLU1G32CMUTCG NLV14001UBDR2G NLVVHC1G132DTT1G NLVVHC1G86DTT1G NLX1G11AMUTCG NLX1G97MUTCG 746427X 74AUP1G17FW5-7 74LS38 74LVC1G08Z-7 74LVC32ADTR2G 74LVC1G125FW4-7 74LVC08ADTR2G MC74HCT20ADTR2G NLU1G08CMX1TCG NLV14093BDTR2G NLV17SZ00DFT2G NLV17SZ02DFT2G NLV17SZ126DFT2G NLV27WZ17DFT2G NLV74HC02ADR2G NLV74HC08ADR2G NLVVHC1GT32DFT1G 74HC32S14-13 74LS133 74LVC1G32Z-7 M38510/30402BDA 74LVC1G86Z-7 74LVC2G08RA3-7 M38510/06202BFA NLV74HC08ADTR2G NLV74HC14ADR2G